

206CMQ200 SCHOTTKY RECTIFIER

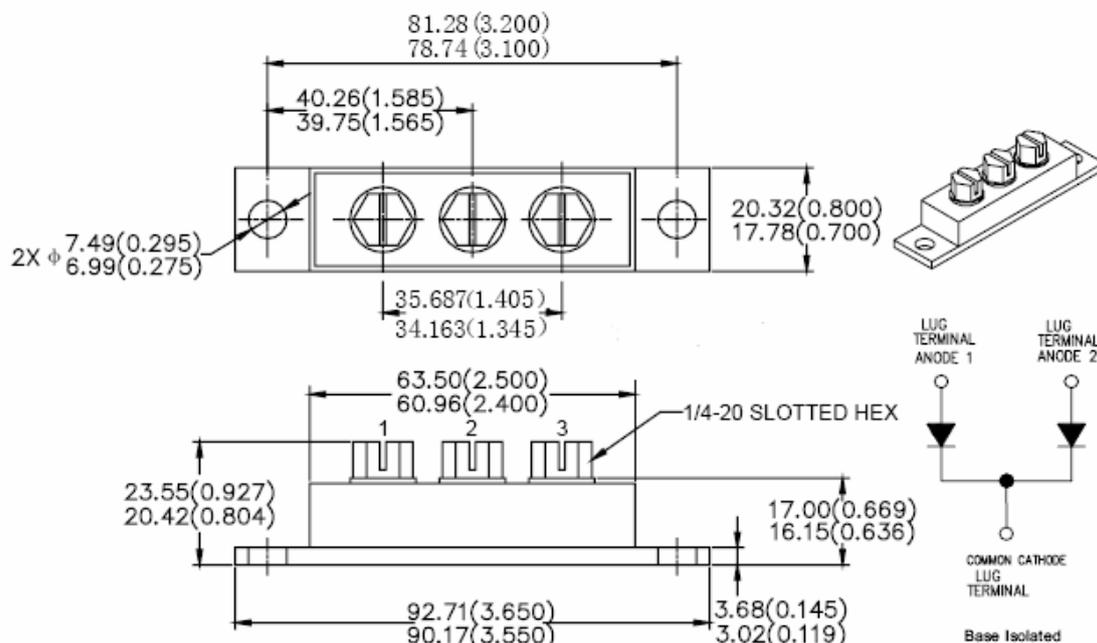
Applications:

- High current switching power supply • Plating power supply • Free-Wheeling diodes
- Reverse battery protection • Converters • UPS System • Welding

Features:

- 175°C T_J operation
- Center tap module
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Low forward voltage drop
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- This is a Pb - Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Mechanical Dimensions: In mm/Inches



Please Note: Anode 1 = Terminal 1; Anode 2 = Terminal 3; Common Cathode = Terminal 2
Suffix R Denotes for Reversed Polarity.

PRM4 (Isolated)

MARKING, MOLDING RESIN

Marking for 206CMQ200, 1st row SS YYWWL, 2nd row 206CMQ200

Where YY is the manufacture year

WW is the manufacture week code

L is the wafer's Lot Number

Molding resin

Epoxy resin UL:94V-0

Technical Data
Data Sheet N1010, Rev. C
Maximum Ratings:
Green Products

Characteristics	Symbol	Condition	Max.	Units
Peak Inverse Voltage	V_{RWM}	-	200	V
Max. Average Forward Current	$I_{F(AV)}$	50% duty cycle @ $T_C=121^{\circ}C$, rectangular wave form	100 200	per leg per device
Max. Peak One Cycle Non-Repetitive Surge Current (per leg)	I_{FSM}	8.3 ms, half Sine pulse	3840	A

Electrical Characteristics:

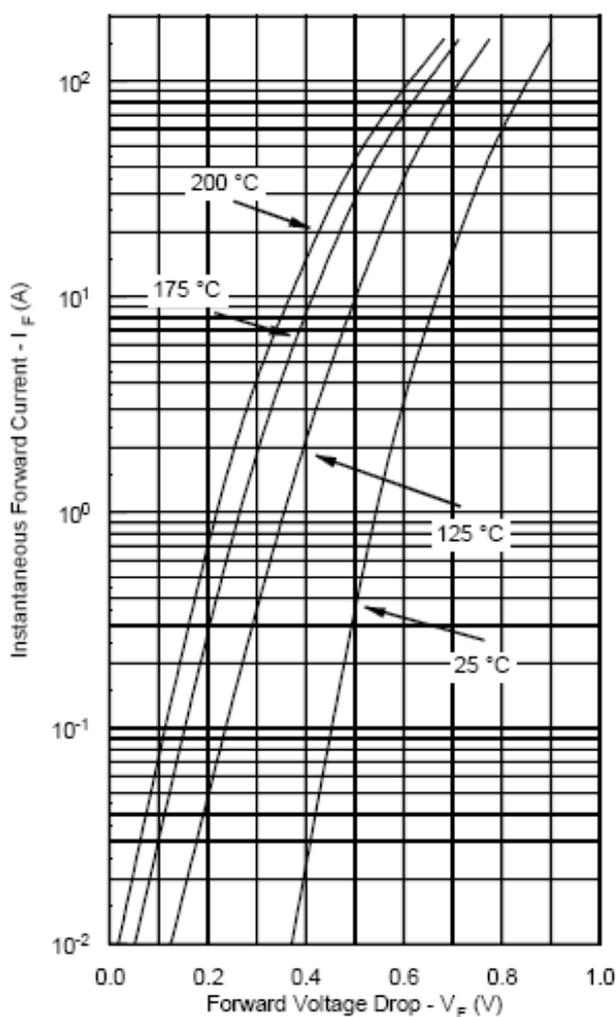
Characteristics	Symbol	Condition	Max.	Units
Max. Forward Voltage Drop (per leg) *	V_{F1}	@ 100A, Pulse, $T_J = 25^{\circ}C$ @ 200A, Pulse, $T_J = 25^{\circ}C$	0.86 1.03	V
	V_{F2}	@ 100A, Pulse, $T_J = 125^{\circ}C$ @ 200A, Pulse, $T_J = 125^{\circ}C$	0.76 0.86	V
Max. Reverse Current at DC condition	I_{R1}	@ $V_R = \text{rated } V_R$ $T_J = 25^{\circ}C$	10	mA
Max. Reverse Current	I_{R2}	@ $V_R = \text{rated } V_R$ $T_J = 125^{\circ}C$	90	mA
Max. Junction Capacitance	C_T	@ $V_R = 5V$, $T_C = 25^{\circ}C$ $f_{SIG} = 1MHz$	2000	pF
Max. Voltage Rate of Change (Rated V_R)	dv/dt	-	10,000	V/ μs

* Pulse Width < 300 μs , Duty Cycle < 2%

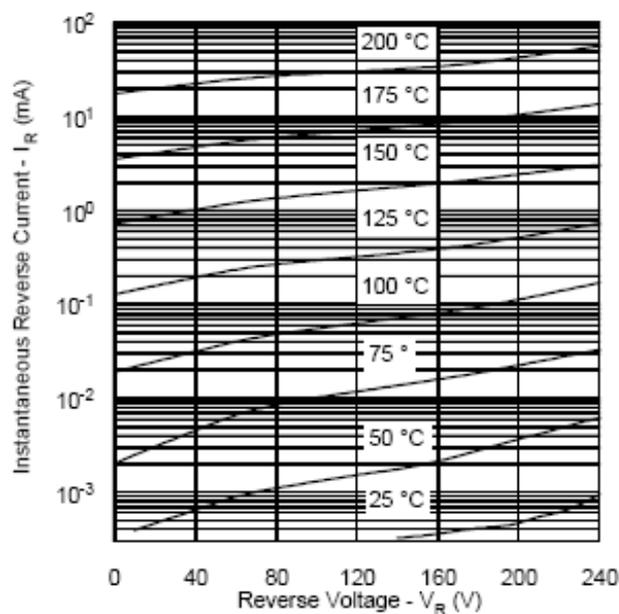
Thermal-Mechanical Specifications:

Characteristics	Symbol	Condition	Specification	Units
Max. Junction Temperature	T_J	-	-55 to +175	$^{\circ}C$
Max. Storage Temperature	T_{stg}	-	-55 to +175	$^{\circ}C$
Maximum Thermal Resistance Junction to Case (per leg)	$R_{\theta JC}$	DC operation	0.7	$^{\circ}C/W$
Maximum Thermal Resistance Junction to Case (per device)	$R_{\theta JC}$	DC operation	0.35	$^{\circ}C/W$
Typical Thermal Resistance, case to Heat Sink	$R_{\theta cs}$	Mounting surface, smooth and greased	0.10	$^{\circ}C/W$
Mounting Torque	T_M	-	Mounting Torque	24(min) 35(max)
			Terminal Torque	35(min) 46(max)
Approximate Weight	wt	-	79	g
Case Style	PRM4 (Isolated)			

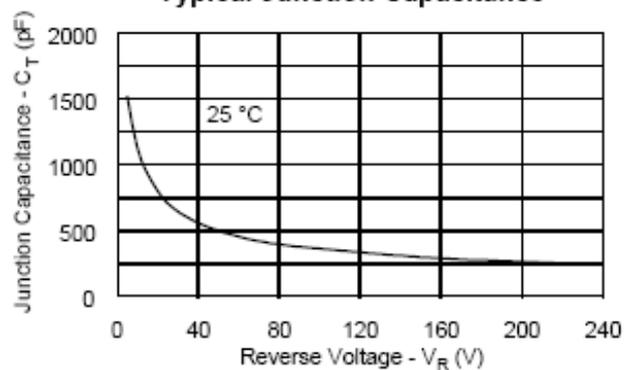
Typical Forward Characteristics



Typical Reverse Characteristics



Typical Junction Capacitance



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